



Feature

- Draft Angle A
- Draft Angle B
- Package Corner Radius R
- External Lead Shoulder Length C
- Mold Ejector Pin Marks on Top of Package D

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MOTOROLA

Engineering Bulletin MC68302FC 132-Lead P

Motorola is pleased to announce improvements in th 132-lead PQFP. The manufacturability improvement (Carrier Ring) assembly process flow and 2) impleme non-MCR assembly process flow has already been i PQFP, and is currently running in volume production

Extensive assembly characterization data including, yield data, was collected to demonstrate either equi available for review on customer request.

The implementation of the non-MCR manufacturab internal to the package or any package construction the existing product case outline will continue to be 68302 products processed with non-MCR process an shown on the following page.

This document contains information on a new product under development Motorola reserves the right to change or discontinue this product without n

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